



RE900-05

- Epoxy fibre-glass FR4 1.50 mm
- Double-sided 35 µm Cu
- Plated through holes (PTH)
- Surface chem. Ni/Au with solder stop mask
- Adaption circuit board for TSOP II 40, 44 (0.80 mm)
- Hole diameter 1.00 mm
- Gerber data for manufacture of the soldering paste imprint will be provided free of charge on request
- Size 29.29 x 30.94 mm

Module-No.	Typ	Pitch	Pin	Size (mm)
RE900-05	TSOP II	0.800 mm	40, 44	11.50 x 18.80